IPC ASSOCIATION ELECTRONIC	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				Materials and	ials and Mfg Information				
upplier	r Information													
ompany	name*	Company ur	Company unique ID			Unique ID Authority				Response Date*				
nsemi											2024-04-24			
Contact N	ame	Title - Conta	Title - Contact			Phone - Contact*				Email - Contact*				
Product-H	Env-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorize	d Representative*	Title - Repre	Title - Representative			Phone - Representative*			Ema	Email - Representative*				
Product-Env-Stewards Pr			Product Env	Product Enviro Compliance			NA			Pro	Product-Env-Stewards@onsemi.com			
	Requester Item Number	Mfr Iten	Mfr Item Number Mfr Item Name				Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
		FSB50825AT SPM5 INV 500		SPM5 INV 500V	0.45ohm		2024-04-24		СРА		3214.74	mg	Each	
lanufa	cturing Process Inform		Tompinal Daga	Aller	-STD-020 MSL	Dating	Dools Duogo	Dody Tampar	ture May Time	at Daals Town	onotium Niversh	on of Doflaw Cv	olog	
	3		Terminal Base Alloy J-STD-02 CU Alloy NA			. Kating	0	rak Process Body Temperature Max Time at Per		1	seconds 3 Number of Reflow Cycles			
	, ,		CU Alloy	I	(A		Į v		30	se	conds 3			
omments	i													
	information regarding materia		1											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and/Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	20.5	mg	Supplier	Silicon (Si)	7440-21-3		20.5	mg
Die Attach	1.3	mg	Supplier	Silver (Ag)	7440-22-4		0.988	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.312	mg
Die Attach Solder	4.0	mg	Supplier	Silver (Ag)	7440-22-4		0.1	mg
			A	Lead (Pb)	7439-92-1	7a	3.7	mg
			Supplier	Tin (Sn)	7440-31-5		0.2	mg
Lead Frame	1351.45	mg	Supplier	Silver (Ag)	7440-22-4		19.7	mg
			Supplier	Iron (Fe)	7439-89-6		1.35	mg
			Supplier	Copper (Cu)	7440-50-8		1329.9956	mg
			Supplier	Phosphorus (P)	7723-14-0		0.4044	mg
Mold Compound-Black	1822.19	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		264.0007	mg
			Supplier	Carbon Black (C)	1333-86-4		8.19	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1549.9993	mg
Plating	13.8	mg	Supplier	Tin (Sn)	7440-31-5		13.8	mg
Wire Bond - Cu	1.5	mg	Supplier	Palladium (Pd)	7440-05-3		0.03	mg
			Supplier	Copper (Cu)	7440-50-8		1.47	mg